

REV.	REVISIONS DESCRIPTION	DATE	APPROVED
-	INITIAL RELEASE	4/18/2011	D. NGUYEN
NOTES: DIMENSION ARE INCHES UNLESS OTHERWISE SPECIFIED			
1. CONSTRUCTION: 1 oz. Cu TOP LAYER, ROGERS 4003, 8 MIL THICK DIELECTRIC, 1 oz. Cu BOTTOM LAYER, FINISHED BOARD THICKNESS APPROX 14 MILS SOLDERMASK TOPSIDE ONLY, COLOR - BLUE			
2. FINISH PLATING: a. NICKEL TYPE: ASTM B733-97, CLASS1, 3-8 um THICK, 7-9% PHOSPHORUS. b. GOLD TYPE: IMMERSION GOLD .03 - .2 um THICK			
3. HOLE PLATING: COPPER MIN. .0008.			
4. MECHANICAL/HOLE LOCATION TOLERANCES: MECHANICAL ±.005, HOLE LOCATION TOLERANCE ±.003 TO TOP VIEW, TOP LAYER.			
5. PATTERN ACCURACY ±.001 FROM 1:1 ARTWORK.			
6. MUST COMPLY WITH EU ROHS DIRECTIVE 2002/95/EC.			
7.8. SEE SHEET 2			
9,10,11. SEE SHEET 4			
12. SEE SHEET 5			

DIMENSIONS ARE IN INCHES, UNLESS OTHERWISE SPECIFIED.		SIGNATURES		DATE
DEC.XX=±.020	FRA.C.±	D. NGUYEN		4/18/2011
.XXX=±.005	ANG.±			
XXXX=±.0020	ENG.			
REMOVE BURRS, BREAK SHARP EDGES				
MATERIAL:				
SEE NOTES				
FINISH:				
SEE NOTES				

THAQUINT

SEMICONDUCTOR

500 W Renner Road
Richardson, Texas
32850-5901
Tel: (972) 894-5696

SIZE

DWG.NO.

REV

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TGA2535/3-SM_PCB_Fpb-

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Printed Circuit Board – Fabrication

SCALE: NONE

SHEET 1 OF 5

SEE NOTE 7

SEE NOTE 8

7. LETTERING SHOWN TO BE SILKSCREENED ON TOP OF FINISHED BOARD.

8. SILKSCREEN THE FOLLOWING ON TOP LAYER, IN AN AREA THAT DOES NOT INTERFERE WITH ANY FEATURES:
-TRIQUINT DOCUMENT NUMBER AND REVISION.
-MANUFACTURER NAME OR LOGO.
-DATE CODE.

SIZE

DWG.NO.

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SCALE: NONE

SHEET 2 OF 5